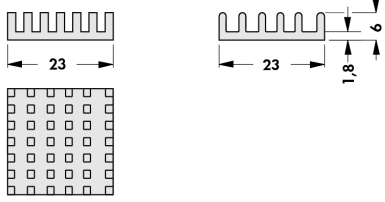
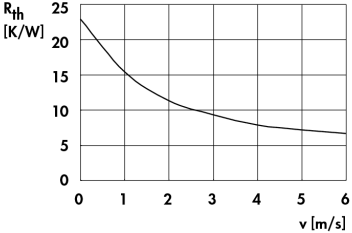
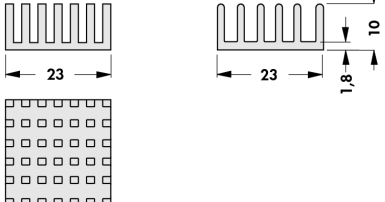
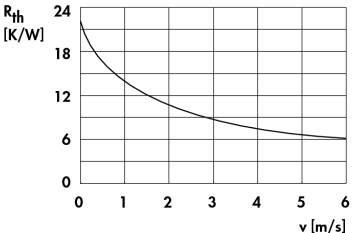
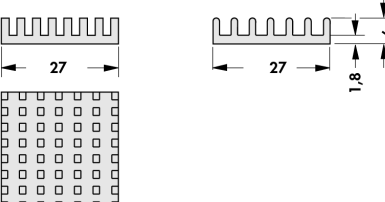
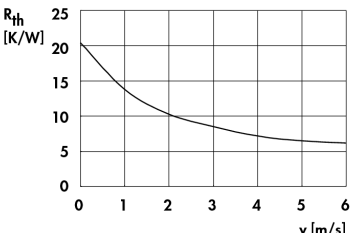
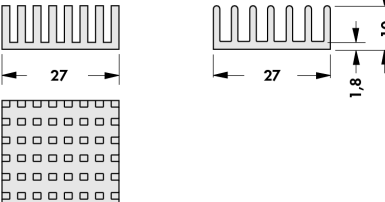
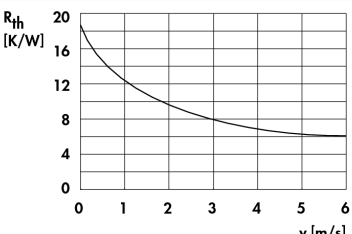
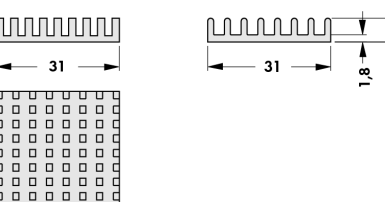
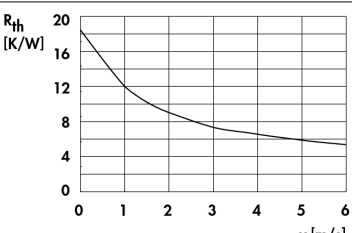
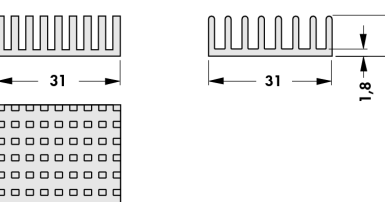
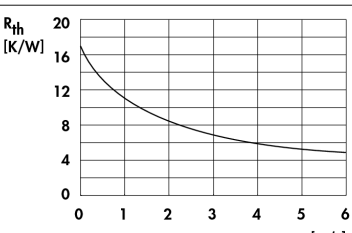


<p><b>art. no.</b></p> <p><b>ICK BGA 23 x 23</b> WLF ... 23 x 23</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 23 x 23 x 10</b> WLF ... 23 x 23</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 27 x 27</b> WLF ... 27 x 27</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 27 x 27 x 10</b> WLF ... 27 x 27</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 31 x 31</b> WLF ... 31 x 31</p>		
<p><b>art. no.</b></p> <p><b>ICK BGA 31 x 31 x 10</b> WLF ... 31 x 31</p>		

Thermal conduct. foil WLF 404/405 → E 5  
 Thermal conductive glue → E 14  
 Thermal conductive paste → E 12  
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27  
 Mounting material for semiconduct. → E 34 - 38  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7

**B 14**